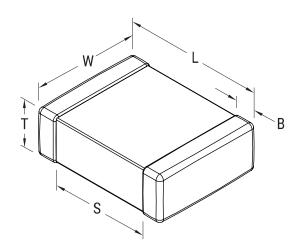


C1206C821JGRACTU

Aliases (C1206C821JGRAC7800) SMD Comm X7R HV, Ceramic, 820 pF, 5%, 2,000 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 1206, 1.5 mm



Click here for the 3D model.

2500

| General Information | | |
|--------------------------|--|--|
| Series | SMD Comm X7R HV | |
| Style | SMD Chip | |
| Description | SMD, MLCC, High Voltage, Temperature Stable | |
| Features | High Voltage | |
| RoHS | Yes | |
| Termination | Tin | |
| Marking | No | |
| AEC-Q200 | No | |
| Typical Component Weight | 31 mg | |
| Shelf Life | 78 Weeks | |
| MSL | 1 | |

| | | Specifications |
|-------------|--------------------------|---------------------------------|
| | 1206 | Capacitance |
| | 3.2mm +/-0.2mm | Measurement Condition |
| | 1.6mm +/-0.2mm | Tolerance |
| | 1.2mm +/-0.15mm | Voltage DC |
| | 1.5mm MIN | Dielectric Withstanding Voltage |
| | 0.5mm +/-0.25mm | Temperature Range |
| | | Temp. Coefficient |
| cifications | | Capacitance Change with |
| | T&R, 180mm, Plastic Tape | Reference to +25°C and 0 VDC |

| | Specifications | |
|--|--|--|
| | Capacitance | 820 pF |
| | Measurement Condition | 1 kHz 1.0Vrms |
| | Tolerance | 5% |
| | Voltage DC | 2000 VDC |
| | Dielectric Withstanding Voltage | 2,400 VDC |
| | Temperature Range | -55/+125°C |
| | Temp. Coefficient | X7R |
| | Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| | Dissipation Factor | 2.5%1kHz1.0Vrms |
| | Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| | Insulation Resistance | 100 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions Chip Size

Packaging Spec Packaging

Packaging Quantity

L W T S B